MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

| Rating | Symbol | Value | Unit |
|---|--|------------------------|------------------|
| Peak Repetitive Off–State Voltage (Note 1) $ (T_J = -40 \text{ to } 110^\circ\text{C}, \text{ Sine Wave}, \\ 50 \text{ to } 60 \text{ Hz}, R_{GK} = 1 \text{ k}\Omega) & 2\text{N}5060 \\ & 2\text{N}5061 \\ & 2\text{N}5062 \\ & 2\text{N}5064 $ | V _{DRM} , V _{RRM} | 30 60 100 200 | V |
| On-State Current RMS (180° Conduction Angles; T _C = 80°C) | I _{T(RMS)} | 0.8 | Α |
| *Average On-State Current (180 $^{\circ}$ Conduction Angles) (T_{C} = 67 $^{\circ}$ C) (T_{C} = 102 $^{\circ}$ C) | l _{T(AV)} | 0.51 0.255 | А |
| *Peak Non-repetitive Surge Current, T _A = 25°C (1/2 cycle, Sine Wave, 60 Hz) | I _{TSM} | 10 | А |
| Circuit Fusing Considerations (t = 8.3 ms) | l ² t | 0.4 | A ² s |
| *Average On-State Current (180 $^{\circ}$ Conduction Angles) (T_{C} = 67 $^{\circ}$ C) (T_{C} = 102 $^{\circ}$ C) | I _{T(AV)} | 0.51 0.255 | A |
| *Forward Peak Gate Power (Pulse Width ≤ 1.0 µsec; T _A = 25°C) | P _{GM} | 0.1 | W |
| *Forward Average Gate Power (T _A = 25°C, t = 8.3 ms) | P _{G(AV)} | 0.01 | W |
| *Forward Peak Gate Current (Pulse Width ≤ 1.0 µsec; T _A = 25°C) | I _{GM} | 1.0 | Α |
| *Reverse Peak Gate Voltage (Pulse Width $\leq 1.0 \mu sec; T_A = 25^{\circ}C$) | V_{RGM} | 5.0 | V |
| *Operating Junction Temperature Range | TJ | -40 to +110 | °C |
| *Storage Temperature Range | T _{stg} | -40 to +150 | °C |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL CHARACTERISTICS

| Characteristic | Symbol | Max | Unit |
|--|----------------|-----|------|
| *Thermal Resistance, Junction-to-Case (Note 2) | $R_{	heta JC}$ | 75 | °C/W |
| Thermal Resistance, Junction-to-Ambient | $R_{	heta JA}$ | 200 | °C/W |

^{2.} This measurement is made with the case mounted "flat side down" on a heatsink and held in position by means of a metal clamp over the curved surface.

V_{DRM} and V_{RRM} for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; however, positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.

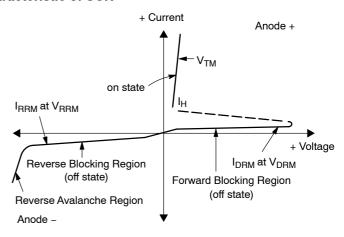
^{*}Indicates JEDEC Registered Data.

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

| Characteristic | | Symbol | Min | Тур | Max | Unit |
|--|--|-------------------------------------|--------|------------|------------|--------------------------|
| OFF CHARACTERISTICS | | • | | • | • | • |
| *Peak Repetitive Forward or Reverse Blocking Current (I $(V_{AK} = Rated\ V_{DRM}\ or\ V_{RRM})$ | Note 3) T _C = 25°C T _C = 110°C | I _{DRM} , I _{RRM} | _ _ | - - | 10 50 | μ Α μ Α |
| ON CHARACTERISTICS | | | | | | |
| *Peak Forward On-State Voltage (Note 4) (I _{TM} = 1.2 A peak @ T _A = 25°C) | | V _{TM} | - | _ | 1.7 | V |
| Gate Trigger Current (Continuous DC) (Note 5) $*(V_{AK} = 7.0 \text{ Vdc}, R_L = 100 \Omega)$ | $T_C = 25^{\circ}C$ $T_C = -40^{\circ}C$ | l _{GT} | - - | - - | 200 350 | μΑ |
| Gate Trigger Voltage (Continuous DC) (Note 5) *(V_{AK} = 7.0 Vdc, R_L = 100 Ω) | $T_C = 25^{\circ}C$ $T_C = -40^{\circ}C$ | V _{GT} | - | - - | 0.8 1.2 | V |
| *Gate Non-Trigger Voltage $(V_{AK} = Rated V_{DRM}, R_L = 100 \Omega) T_C = 110^{\circ}C$ | | V _{GD} | 0.1 | - | - | V |
| Holding Current (Note 3) *(V _{AK} = 7.0 Vdc, initiating current = 20 mA) | $T_C = 25^{\circ}C$ $T_C = -40^{\circ}C$ | IH | - - | - - | 5.0 10 | mA |
| Turn-On Time Delay Time Rise Time $(I_{GT}=1.0 \text{ mA, } V_D=\text{Rated } V_{DRM},$ Forward Current = 1.0 A, di/dt = 6.0 A/ μ s | | t _d t _r | - - | 3.0 0.2 | - - | μs |
| Turn-Off Time (Forward Current = 1.0 A pulse, Pulse Width = 50 μ s, 0.1% Duty Cycle, di/dt = 6.0 A/ μ s, dv/dt = 20 V/ μ s, I _{GT} = 1 mA) 2N5060, 2N50 | | tq | - | 10 30 | - | μs |
| 2N5062, 2N50 DYNAMIC CHARACTERISTICS | U 4 | | | 30 | _ | <u> </u> |
| Critical Rate of Rise of Off–State Voltage (Rated V _{DRM} , Exponential, R _{GK} = 1 kΩ) | | dv/dt | _ | 30 | - | V/µs |

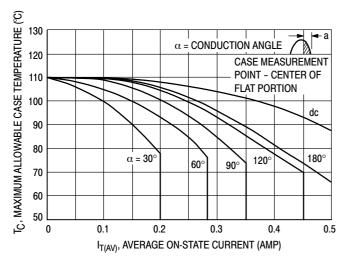
Voltage Current Characteristic of SCR

| Symbol | Parameter |
|------------------|---|
| V _{DRM} | Peak Repetitive Off State Forward Voltage |
| I _{DRM} | Peak Forward Blocking Current |
| V _{RRM} | Peak Repetitive Off State Reverse Voltage |
| I _{RRM} | Peak Reverse Blocking Current |
| V_{TM} | Peak on State Voltage |
| I _H | Holding Current |



^{3.} $R_{GK} = 1000 \,\Omega$ is included in measurement.
4. Forward current applied for 1 ms maximum duration, duty cycle \leq 1%.
5. R_{GK} current is not included in measurement.
*Indicates JEDEC Registered Data.

CURRENT DERATING

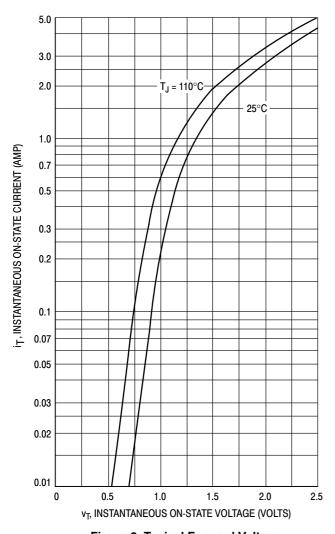


130 TA, MAXIMUM ALLOWABLE AMBIENT α = CONDUCTION ANGLE 110 TEMPERATURE (°C) TYPICAL PRINTED CIRCUIT BOARD 90 MOUNTING 70 dc 50 180 $\alpha = 30^{\circ}$ 60 30 0 0.1 0.2 0.4 I_{T(AV)}, AVERAGE ON-STATE CURRENT (AMP)

Figure 1. Maximum Case Temperature

Figure 2. Maximum Ambient Temperature

CURRENT DERATING





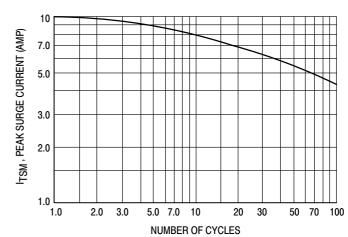


Figure 4. Maximum Non-Repetitive Surge Current

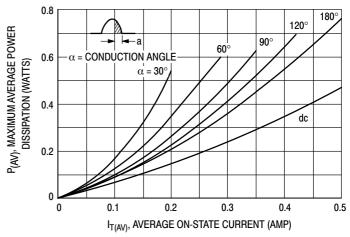


Figure 5. Power Dissipation

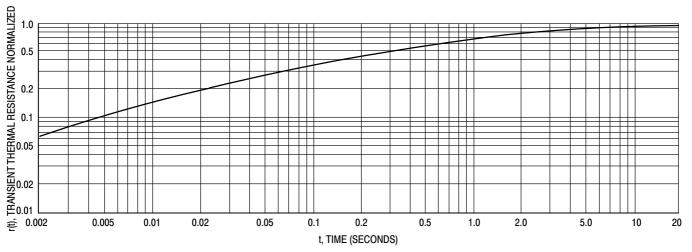
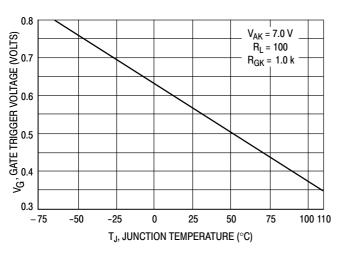


Figure 6. Thermal Response

TYPICAL CHARACTERISTICS



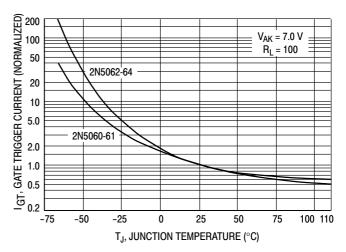


Figure 7. Typical Gate Trigger Voltage

Figure 8. Typical Gate Trigger Current

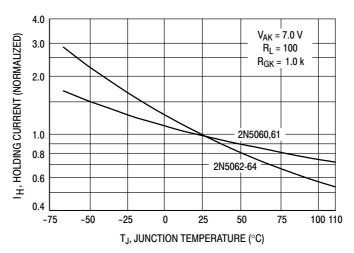


Figure 9. Typical Holding Current

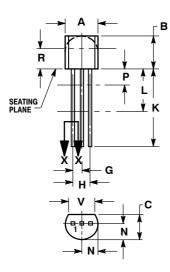
ORDERING INFORMATION

| Device | Package | Shipping [†] |
|-------------|--------------------|-----------------------|
| 2N5060 | TO-92 | 5,000 Units / Box |
| 2N5060G | TO-92 (Pb-Free) | 5,000 Units / Box |
| 2N5060RLRA | TO-92 | 2,000 / Tape & Reel |
| 2N5060RLRAG | TO-92 (Pb-Free) | 2,000 / Tape & Reel |
| 2N5060RLRM | TO-92 | 2,000 / Ammo Pack |
| 2N5060RLRMG | TO-92 (Pb-Free) | 2000 / Ammo Pack |
| 2N5061 | TO-92 | 5,000 Units / Box |
| 2N5061G | TO-92 (Pb-Free) | 5,000 Units / Box |
| 2N5061RLRA | TO-92 | 2,000 / Tape & Reel |
| 2N5061RLRAG | TO-92 (Pb-Free) | 2,000 / Tape & Reel |
| 2N5062 | TO-92 | 5,000 Units / Box |
| 2N5062G | TO-92 (Pb-Free) | 5,000 Units / Box |
| 2N5062RLRA | TO-92 | 2,000 / Tape & Reel |
| 2N5062RLRAG | TO-92 (Pb-Free) | 2,000 / Tape & Reel |
| 2N5064 | TO-92 | 5,000 Units / Box |
| 2N5064RLRA | TO-92 | 2,000 / Tape & Reel |
| 2N5064RLRM | TO-92 | 2,000 / Ammo Pack |
| 2N5064RLRMG | TO-92 (Pb-Free) | 2,000 / Ammo Pack |
| 2N5064RLRAG | TO-92 (Pb-Free) | 2000 / Tape & Reel |
| 2N5064G | TO-92 (Pb-Free) | 5000 Units / Box |

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

TO-92 (TO-226) CASE 29-11 **ISSUE AM**



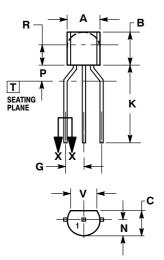
STRAIGHT LEAD **BULK PACK**



NOTES

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
- CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
- LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

| | INCHES | | MILLIN | IETERS |
|-----|--------|-------|--------|--------|
| DIM | MIN | MAX | MIN | MAX |
| Α | 0.175 | 0.205 | 4.45 | 5.20 |
| В | 0.170 | 0.210 | 4.32 | 5.33 |
| С | 0.125 | 0.165 | 3.18 | 4.19 |
| D | 0.016 | 0.021 | 0.407 | 0.533 |
| G | 0.045 | 0.055 | 1.15 | 1.39 |
| Н | 0.095 | 0.105 | 2.42 | 2.66 |
| J | 0.015 | 0.020 | 0.39 | 0.50 |
| K | 0.500 | | 12.70 | |
| L | 0.250 | | 6.35 | |
| N | 0.080 | 0.105 | 2.04 | 2.66 |
| Р | | 0.100 | | 2.54 |
| R | 0.115 | | 2.93 | |
| ٧ | 0.135 | | 3.43 | |



BENT LEAD TAPF & RFFI AMMO PACK



NOTES

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS.
- CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
- LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

| | MILLIMETERS | | |
|-----|-------------|------|--|
| DIM | MIN | MAX | |
| Α | 4.45 | 5.20 | |
| В | 4.32 | 5.33 | |
| С | 3.18 | 4.19 | |
| D | 0.40 | 0.54 | |
| G | 2.40 | 2.80 | |
| J | 0.39 | 0.50 | |
| K | 12.70 | | |
| N | 2.04 | 2.66 | |
| P | 1.50 | 4.00 | |
| R | 2.93 | | |
| ٧ | 3.43 | | |

STYLE 10:

PIN 1. CATHODE

- GATE
- 3. ANODE

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